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Source: Saxony Economic Development Corporation (WFS - Wirtschaftsförderung Sachsen GmbH), Silicon Saxony e. V.
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Optimize the Thermal Performance of your Process Equipment

- **Global Leader in Thermal Systems**
  We design and manufacture solutions for semiconductor applications from crystal growth, through front-end wafer processes to back-end assemblies.

- **Deep Knowledge**
  Our solutions are based on deep thermal knowledge, while understanding the semiconductor technology roadmap.

- **Over 450 Patents Worldwide**
  We continue to invest in R&D, global manufacturing and design services.

- **Partner with Watlow**
  We work with your engineers to deliver innovative thermal solutions that improve yield, throughput and cost of ownership.

Your Global Manufacturing IT Specialist

**Our Solutions and Services ...**

- Shop Floor Automation
- Manufacturing Execution System (MES)
- Equipment Engineering System (EES) and Yield Management System (YMS)
- Advanced Planning & Scheduling (APS)
- Real Time Dispatching (RTD)
- ERP Integration

... for your Benefit

- increase efficiency and productivity
- reduce costs and improve quality
- gain transparency and visibility
- achieve entire production control

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www.znt-richter.com
Please visit our booth and enjoy fine food, music and networking.

Date: 8th October 2014 | 5 pm
Location: Booth 1.032

WE LOOK FORWARD TO WELCOMING YOU!